

Lord Adhesives Metech 3503 Palladium Silver Conductor Composition

Category : Polymer , Adhesive

Material Notes:

Designed for use in the manufacture of hybrid circuitry, resistor networks, potentiometers as well as general purpose microcircuitry. It employs a conventional glass bonding mechanism, has wide processing parameters and is optimized for use with high speed printing equipment. Fired conductor exhibits high initial and aged adhesion values and readily accepts tin lead and tin lead silver solders. All information provided by Lord.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Lord-Adhesives-Metech-3503-Palladium-Silver-Conductor-Composition.php

Physical Properties	Metric	English	Comments
Viscosity	200000 - 260000 cP	200000 - 260000 cP	
Thickness	12.0 microns	0.472 mil	Fired

Electrical Properties	Metric	English	Comments
Surface Resistivity per Square	0.030 ohm	0.030 ohm	

Processing Properties	Metric	English	Comments
Shelf Life	12.0 Month @Temperature 25.0 Â°C	12.0 Month @Temperature 77.0 Â°F	

Descriptive Properties	Value	Comments
Adhesion	4-5	lbs; aged (100 hrs. at 150Â°C)
	5-6	lbs; initial
Coverage (cmÂ²/gm)	70-75	Calculated from 50 micron wet film
Line Resolution (microns)	150	
Silver to Palladium Ratio	2.1:1	
Solder Leach Resistance (cycles)	5	Number of 5-second cycles required to leach 50% of a 10 mil wide conductive line using 62Sn/36Pb/2Ag at 230Â°C
Solder Wetting (seconds)	< 3	Time required to 100% solder wet 0.08" x 0.08" pad size using 62Sn/36Pb/2Ag at 230Â°C

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